

HZM6.8MWA

Silicon Planar Zener Diode for Surge Absorb

REJ03G1210-0200
(Previous: ADE-208-851A)
Rev.2.00
Jun 13, 2005

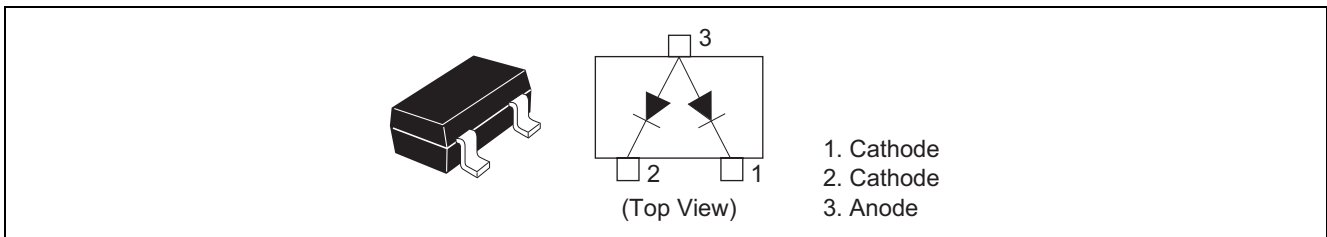
Features

- HZM6.8MWA has two devices in a monolithic, and can absorb surge.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HZM6.8MWA	68M	MPAK	PLSP0003ZC-A (MPAK)

Pin Arrangement



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Power dissipation	Pd *1	200	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Two device total, See Fig.2.

Electrical Characteristics *1

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Zener voltage	V _Z	6.47	—	7.0	V	I _Z = 5 mA, 40 ms pulse
Reverse current	I _R	—	—	2	μA	V _R = 3.5 V
Capacitance	C	—	—	130	pF	V _R = 0 V, f = 1 MHz
Dynamic resistance	r _d	—	—	30	Ω	I _Z = 5 mA
ESD-Capability *2, *3	—	30	—	—	kV	C = 150 pF, R = 330 Ω, Both forward and reverse direction 10 pulse

Notes: 1. Per one device

2. Failure criterion ; I_R > 2 μA at V_R = 3.5 V.

Main Characteristic

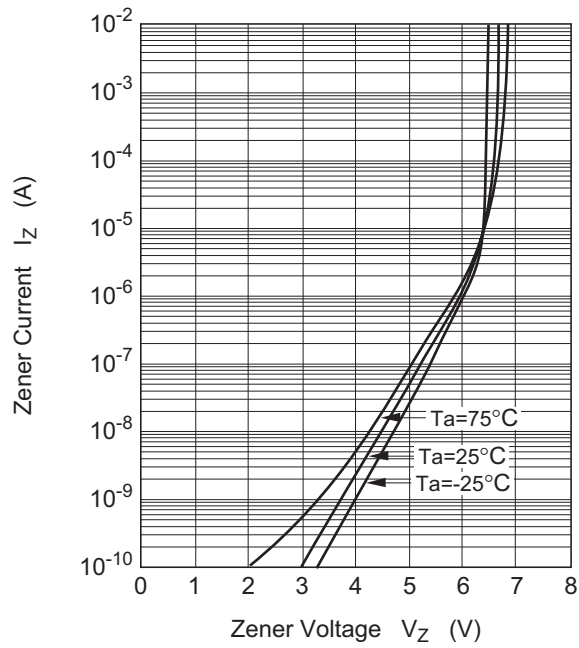


Fig.1 Zener current vs. Zener voltage

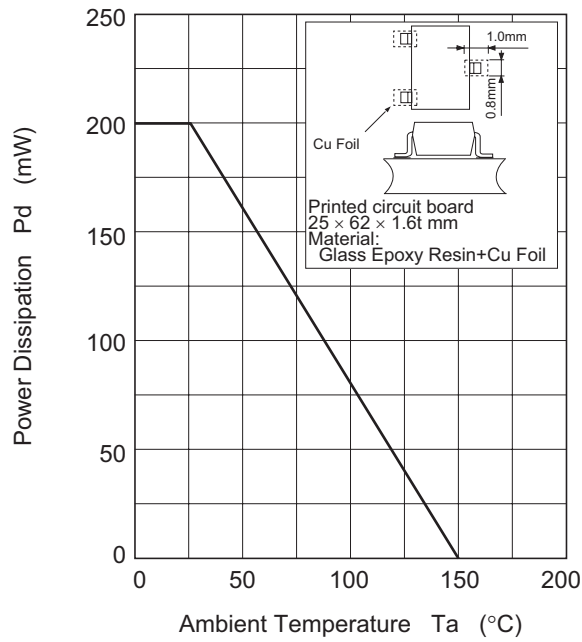
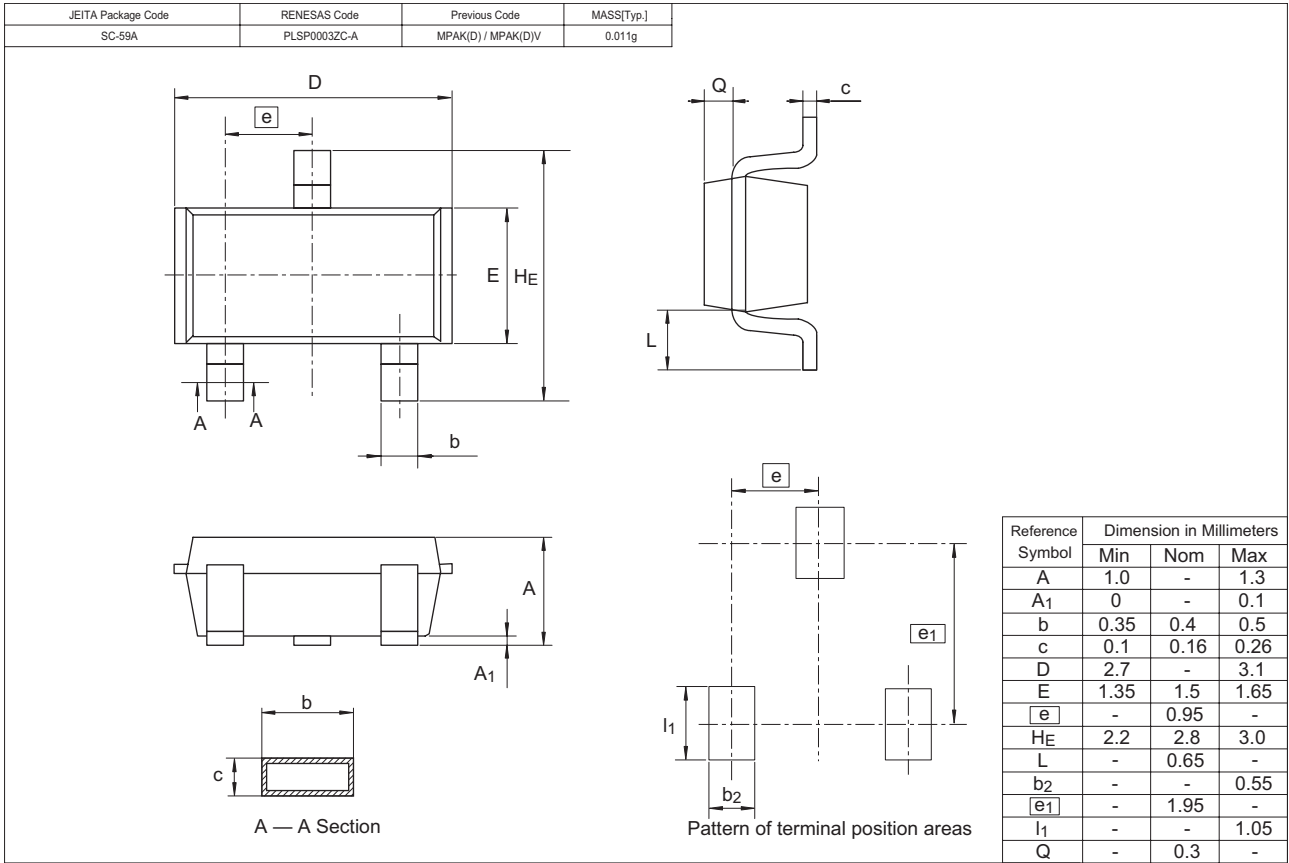


Fig.2 Power Dissipation vs. Ambient Temperature

Package Dimensions



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